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**LMN6292JZF 60V N-Channel MOSFETs**


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**Features**

- 60V, 2.8A,  $R_{DS(ON)}=92m\Omega@V_{GS}=10V$
- Improved dv/dt
- Fast switching
- 100% EAS guaranteed.
- Green Device Available
- SOT-23 package design

minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

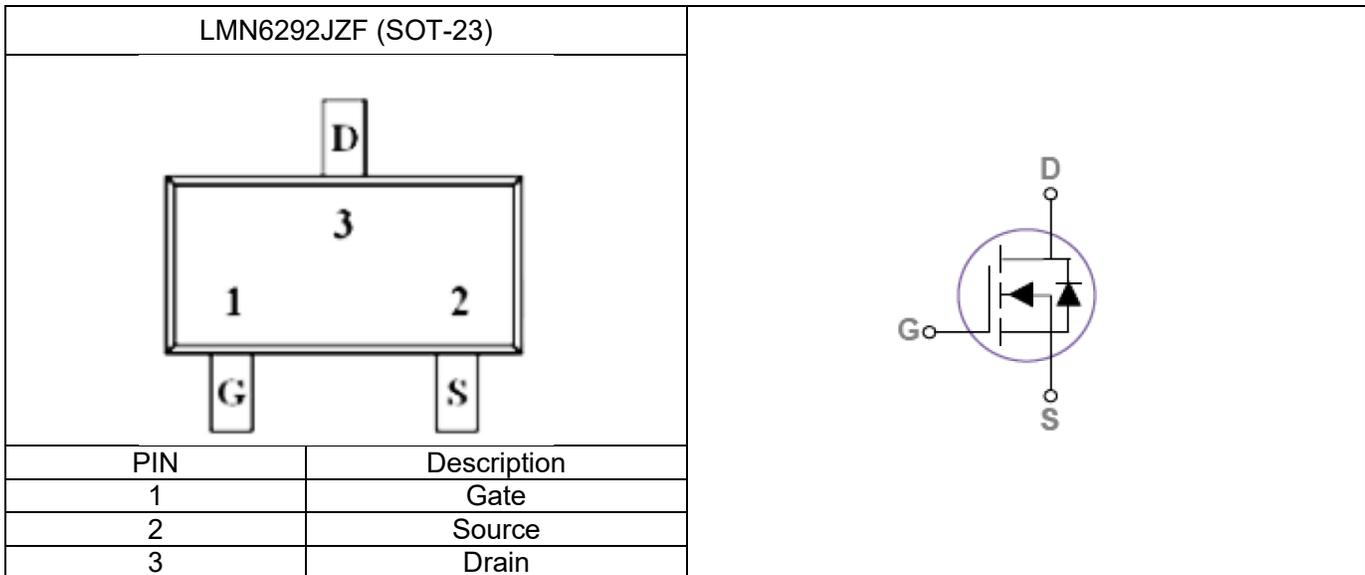
These devices are well suited for high efficiency fast switching applications.

**Product Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to

**Applications**

- Motor Drive
- Power Tools
- LED Lighting

**Pin Configuration**


**Ordering Information**

<u>LMN6292</u>	<u>JZ</u>	<u>E</u>
LFC P/N	PKG code	Pb Free code

**Marking Information**

<u>S3</u>	<u>XWM</u>
Part Number	LFC code

Part Number	Package	Part Marking	Quantity
LMN6292JZF	SOT-23	S3XWM	3000pcs

**Absolute Maximum Ratings**

 (T<sub>C</sub>=25°C Unless otherwise noted)

Symbol	Parameter	Typical	Unit
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current	T <sub>A</sub> =25°C	2.8
		T <sub>A</sub> =70°C	2.2
I <sub>DM</sub>	Pulsed Drain Current	10	A
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> =25°C	1.4
		T <sub>A</sub> =70°C	0.9
T <sub>J</sub>	Operating Junction Temperature Range	-50 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-50 to +150	°C
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient	90	°C/W

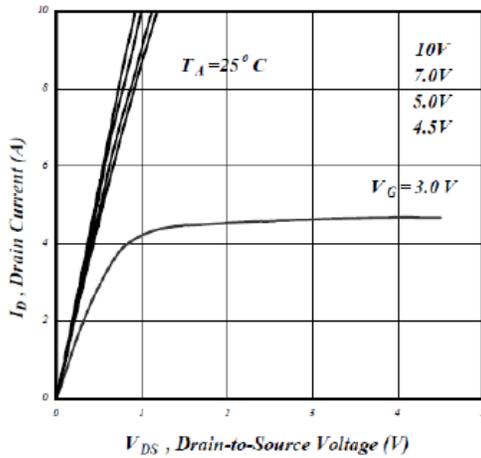
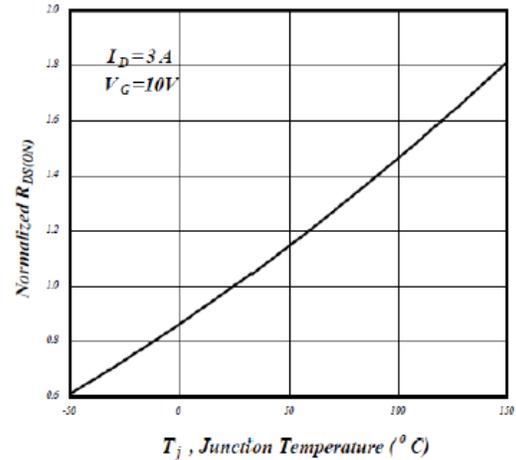
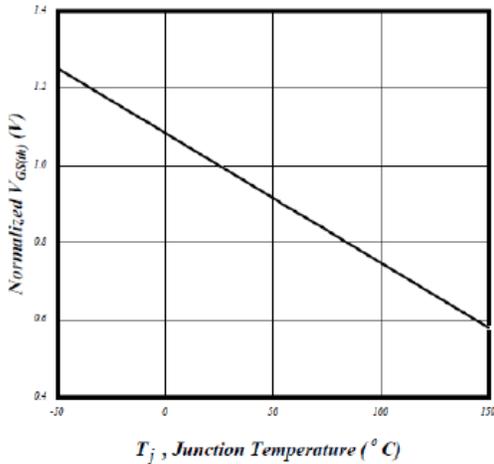
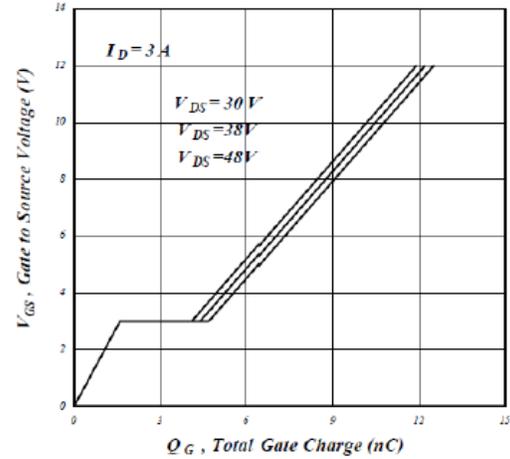
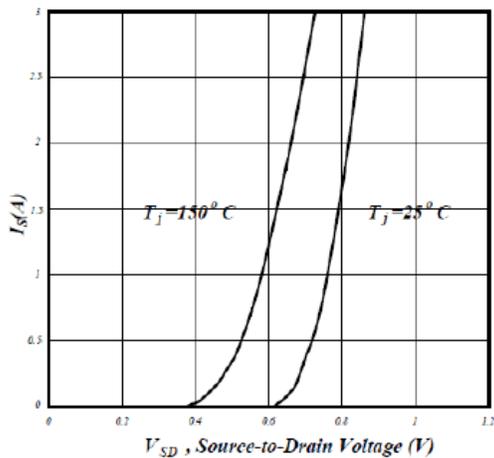
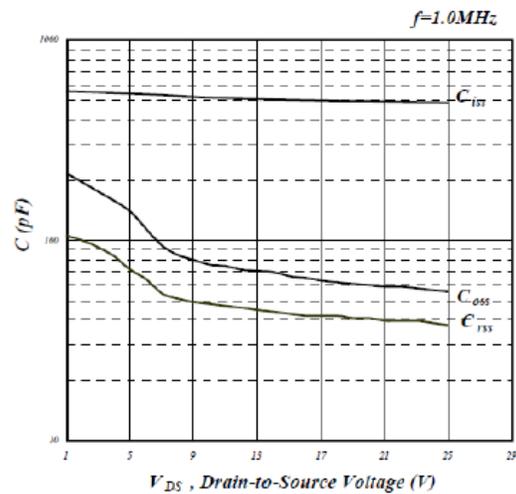
**Electrical Characteristics**

 (T<sub>A</sub>=25°C Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1		3	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			± 100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>A</sub> =125°C			10	
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current			6.1	A
I <sub>SM</sub>	Pulsed Source Current				24.4	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10.0V, I <sub>D</sub> =3A		85	92	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A		90	100	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =3A		3.6		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1.0A, V <sub>GS</sub> =0V			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =3A, V <sub>GS</sub> =0V,		25		Ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs		26		
<b>Dynamic</b>						
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =48V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A		6		nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>			1.3		
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>			3		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz		490		pF
C <sub>oss</sub>	Output Capacitance			55		
C <sub>rss</sub>	Reverse Transfer Capacitance			40		
t <sub>d(on)</sub>	Turn-On Time <sup>2</sup>	V <sub>DD</sub> =30V, I <sub>D</sub> =1A, V <sub>GS</sub> =4.5V, R <sub>G</sub> =6.8Ω		6		ns
t <sub>r</sub>				5		
t <sub>d(off)</sub>	Turn-Off Time <sup>2</sup>			16		
t <sub>f</sub>				3		

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≅ 300us, duty cycle ≅ 2%.
3. Essentially independent of operating temperature.

**Typical Performance Characteristics**

**Fig 1. Typical Output Characteristics**

**Fig. 2 On-Resistance Variation with  $T_j$** 

**Fig. 3 Gate Threshold Variation vs.  $T_j$** 

**Fig. 4 Gate Charge Waveform**

**Fig. 5 Diode Forward Voltage vs. Current**

**Fig. 6 Typical Capacitance**

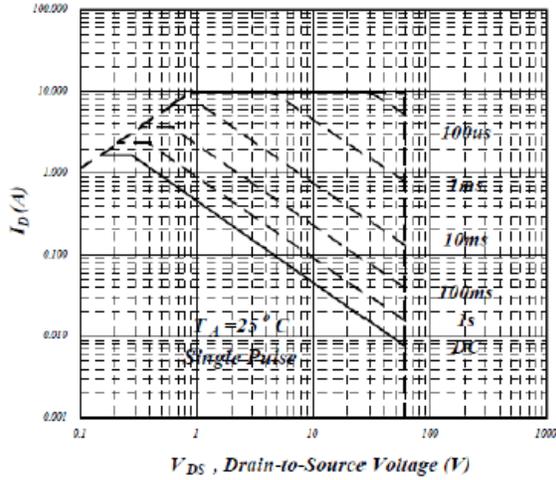


Fig. 7 Maximum Safe Operation Area

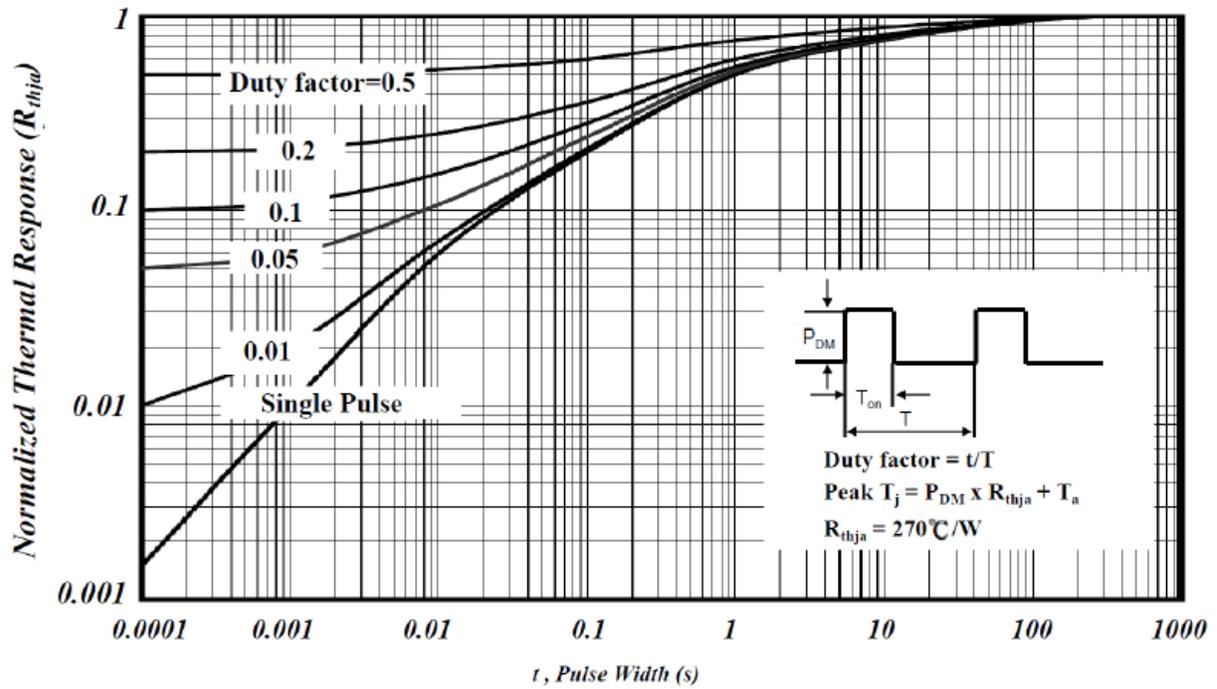
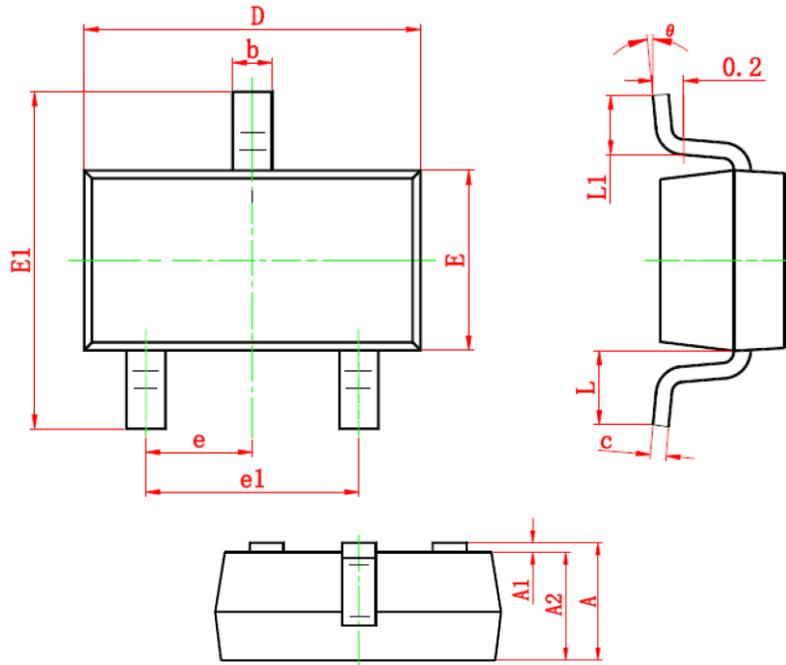


Fig. 11 Transient Thermal Response

**Package Dimension:**
**SOT-23**


Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.200	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.100	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	6°

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